





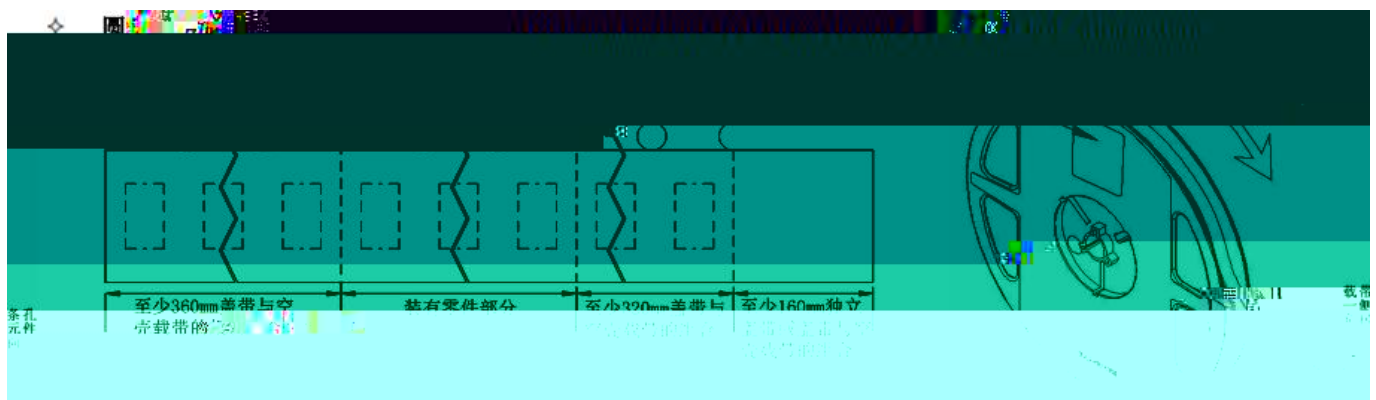
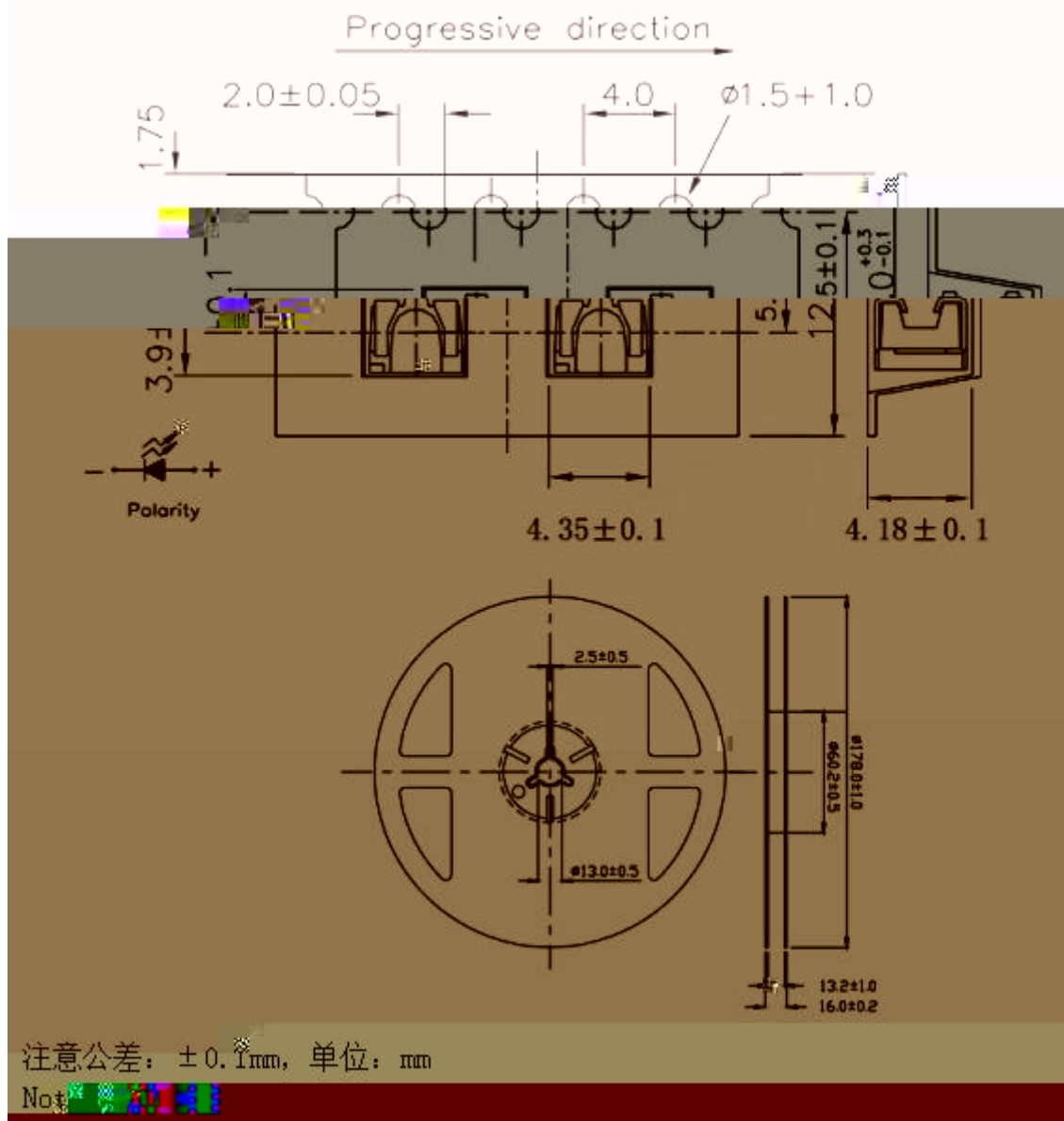




包装 (1)

Packaging (1)

载带与圆盘尺寸, Pitch and disk dimensions



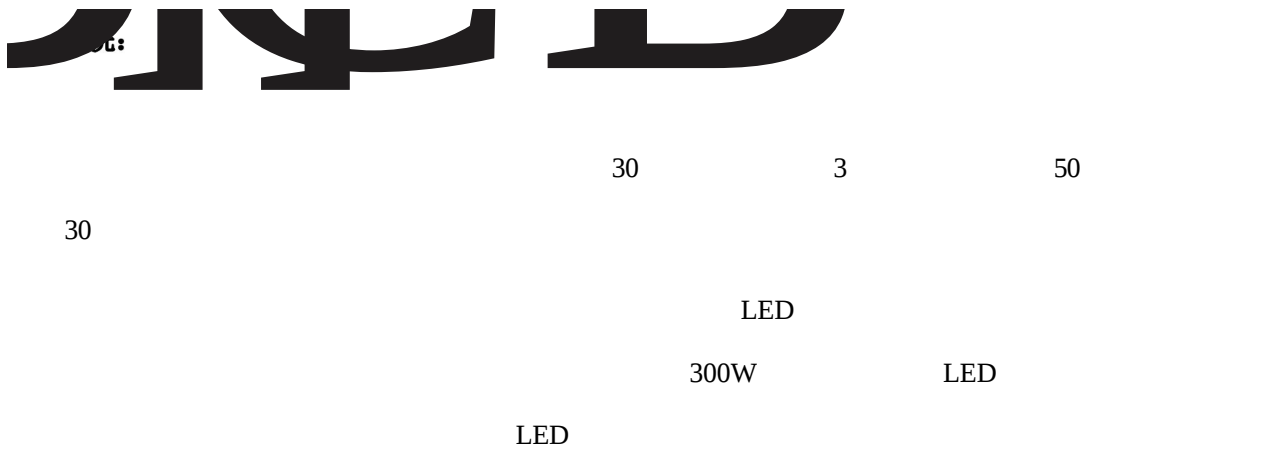


XINGLI



焊接指导 (2)

Guideline for Soldering (2)



It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using solvents, it should be confirmed beforehand whether the solvents will damage the package and the resin or not.

Ultrasonic cleaning is also an effective method for cleaning. But the influence of Ultrasonic cleaning on the package factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pre-test should be conducted to confirm whether any damage to LEDs will occur.

* 注意:

PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The techniques in practice is inf





